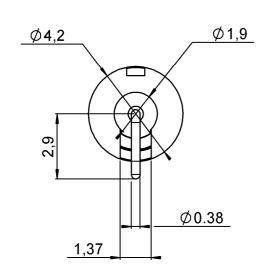
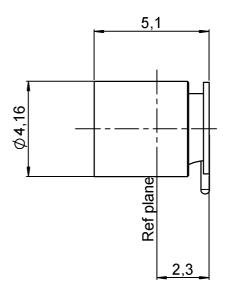
SMT TYPE - SMOOTH BORE - REEL 500

R222.508.700

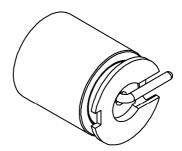
Series: SMP







Scale 1:1



All dimensions are in mm.



	COMPONENTS	MATERIALS	PLATING (μm)
_	BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	STAINLESS STEEL + BRASS BERYLLIUM COPPER - PTFE	PASSIVATED + GOLD 0.5 OVER NICKEL 2 GOLD 0.2 OVER NICKEL PHOSPHORUS 2
	-	-	-

Issue: 0831 C

In the effort to improve our products, we reserve the right to make changes judged to be necessary



SMT TYPE - SMOOTH BORE - REEL 500

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Series: SMP

PACKAGING

Standard	Unit	Other
500	•	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance **50** Ω Frequency **0-12** GHz

VSWR

 $1.15 + 0.0000 \times F(GHz) Maxi$ Insertion loss **0.12** $\sqrt{F(GHz)}$ dB Maxi

NA - F(GHz)) dB Maxi RF leakage - (335 Veff Maxi

Voltage rating Dielectric withstanding voltage 500 Veff mini Insulation resistance **5000** MΩ mini

ENVIRONMENTAL

-65/+165 ° C Operating temperature

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction

Others:

Compliant with MIL-STD-348

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end **6.8** N mini NA N mini Axial force – Opposite end Torque N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 1000 Cycles mini

Weight **0,3200** g

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SMT TYPE - SMOOTH BORE - REEL 500

Series: SMP

SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

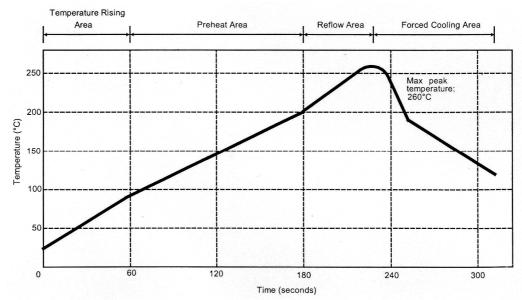
We advise a thickness of $150\,\mu m$ (5.850 microinch). Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit	
Temperature rising Area	1 - 4	°C/sec	
Max Peak Temperature	260	°C	
Max dwell time @260°C	10	sec	
Min dwell time @235°C	20	sec	
Max dwell time @235°C	60	sec	
Temperature drop in cooling Area	-1 to -4	°C/sec	
Max dwell time above 100°C	420	sec	

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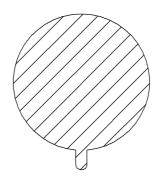


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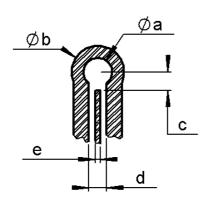
Series: SMP

SHADOW OF THE RECEPTACLE



FOR VIDEO CAMERA

PCB mounting pattern



а	1,91
b	4,45 min.
С	2,29 min.
d	1,52
е	0.38 max.

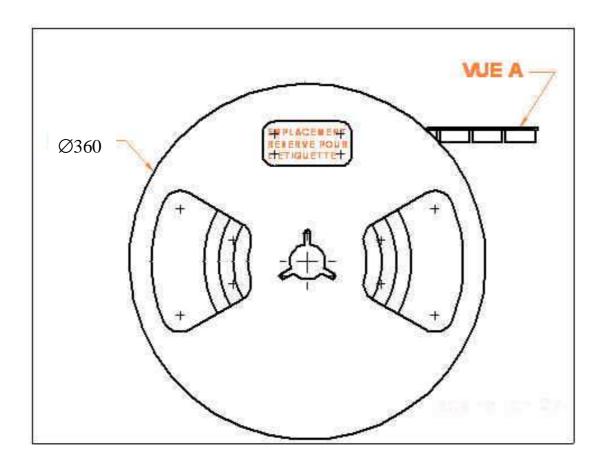
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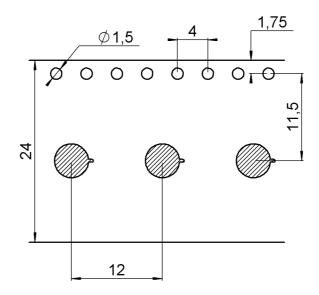


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